

EAST - (10792223 circuit board with opening.wsp:1)

File View Edit Tools Window Help

17: (481) 12 same 15  
18: (96) 17 same 16  
19: (1) 10/793564  
20: (1510823) computer  
21: (25001) 20 with 9  
22: (59822) 17 with 14  
23: (1021 21 same 22  
24: (40) 23 and 11  
25: (27247409) (ad) 20010527  
26: (25) 24 and 25  
27: (274425) computer edj system  
28: (5145) 27 with 9  
29: (1501 21 same 16  
30: (86) 29 and 25  
31: (221 Forward citation search 1  
32: (1) Forward citation search 2  
33: (26) 28 same 16  
34: (14) 33 and 25  
35: (8267) 20 and 25  
36: (285761) 10 near 67  
37: (1019) 35 and 36  
38: (146) 37 and 18  
39: (1136859) cpu processor  
40: (93) 38 and 99  
41: (3) Backward citation search 1

17 same 16

May 2005

U	I	Inventor	Document	Issued	P	Title	Current	Current	K	Retrieval	S	C	P	Image	Def
1		Kinsman, L	US 2004016	2004	13	Bumped die and wire bonded board-on	257/737	257/E21.5							US 200401
2		Kinsman, L	US 668289	2004	12	Methods for bumped die and wire bond	438/61	257/189							US 66828
3		Kinsman, L	US 2004016	2004	13	Bumped die and wire bonded board-on	257/20	257/E21.5							US 200401
4		Funaba, Sei	US 200500	2005	31	Stacked memory, memory module and	365/63	365/51							US 20050
5		Huang, Chi	US 200500	2005	11	Fabrication method of semiconductor	438/80								US 20050
6		Tsai, Chung	US 200500	2005	16	Window ball grid array semiconductor	257/73								US 20050
7		Tsai, Chung	US 200500	2005	16	Window ball grid array semiconductor	257/737	438/618							US 20050
8		Wang, Sung	US 200500	2005	6	Flip chip stacked package	257/778								US 20050
9		Khan, Reza	US 200500	2005	3	Enhanced die-up ball grid array and m	257/73								US 20050
10		Huang, Chi	US 200402	2004	11	Flash-preventing window ball grid arra	257/73								US 20040

Ready

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